# PRAETORIAN® L-C LCD and Camera EMI Array with ESD Protection

#### **Functional Description**

The EMI9408 is an inductor-based (L-C) EMI filter array with ESD protection, which integrates eight filters in a uDFN package with 0.40 mm pitch. Each EMI filter channel of the EMI9408 is implemented with the component 1.8 pF-35 nH-4.7 pF-35 nH-6 pF. The cut-off frequency at 3dB attenuation is 300MHz and can be used in applications where the data rates are as high as 160 Mbps, while providing greater than -35 dB attenuation over the 800 MHz to 2.7 GHz frequency range. The parts include ESD diodes on every I/O pin and provide a high level of protection against electrostatic discharge (ESD). The ESD protection diodes connected to the external filter ports are designed and characterized to safely dissipate ESD strikes of ±14 kV, which is beyond the maximum requirement of the IEC61000-4-2 international standard.

This device is particularly well suited for wireless handsets, mobile LCD modules and PDAs because of its small package format and easy-to-use pin assignments. In particular, the EMI9408 is ideal for EMI filtering and protecting data and control lines for the LCD display and camera interface in mobile handsets.

The EMI9408 is housed in space saving, low profile, 0.40 mm pitch uDFN packages in a RoHS compliant, Pb–Free format.

#### **Features**

- Eight Channels of EMI Filtering with Integrated ESD Protection
- Pi-Style EMI Filters in a Capacitor-Inductor Capacitor (C-L-C) Network
- ±14 kV ESD Protection (IEC 61000-4-2 Level 4, Contact Discharge) at External Pin
- Greater than -35 dB Attenuation (Typical) at 1 GHz
- uDFN Pb-Free Package with 0.40 mm Lead Pitch: 8-ch. = 16-lead uDFN
- uDFN Package Size:

16-Lead: 3.30 mm x 1.35 mm

- Increased Robustness Against Vertical Impacts During Manufacturing Process
- These Devices are Pb-Free and are RoHS Compliant

# **Applications**

- LCD and Camera Data Lines in Mobile Nandsets
- I/O Port Protection for Mobile Handsets, Notebook Computers, PDAs, etc.
- EMI Filtering for Data Ports in Cell Phones, PDAs or Notebook Computer



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# MARKING DIAGRAMS



UDFN16 CASE 517BE



\_E = Spe

= Specific Device Code

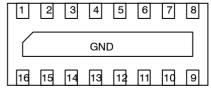
= Month Code

■ = Pb-Free Package

(\*Note: Microdot may be in either location)

#### **PINOUTS**

Internal Pins (Lower ESD Event)

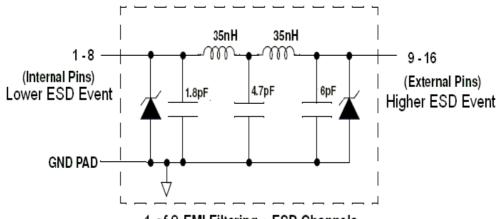


External Pins (Higher ESD Event) (Bottom View)

#### **ORDERING INFORMATION**

See detailed ordering and shipping information in the package dimensions section on page 3 of this data sheet.

- Wireless Handsets
- Handheld PCs/PDAs
- LCD and Camera Modules



1 of 8 EMI Filtering + ESD Channels

Figure 1. Electrical Schematic

**Table 1. PIN DESCRIPTIONS** 

Pin #	Name	Description			
1	FILTER1	Filter + ESD Channel 1 (Internal)			
2	FILTER2	Filter + ESD Channel 2 (Internal)			
3	FILTER3	Filter + ESD Channel 3 (Internal)			
4	FILTER4	Filter + ESD Channel 4 (Internal)			
5	FILTER5	Filter + ESD Channel 5 (Internal)			
6	FILTER6	Filter + ESD Channel 6 (Internal)			
7	FILTER7	Filter + ESD Channel 7 (Internal)			
8	FILTER8	Filter + ESD Channel 8 (Internal)			
9	FILTER8	Filter + ESD Channel 8 (External)			
10	FILTER7	Filter + ESD Channel 7 (External)			
11	FILTER6	Filter + ESD Channel 6 (External)			
12	FILTER5	Filter + ESD Channel 5 (External)			
13	FILTER4	Filter + ESD Channel 4 (External)			
14	FILTER3	Filter + ESD Channel 3 (External)			
15	FILTER2	Filter + ESD Channel 2 (External)			
16	FILTER1	Filter + ESD Channel 1 (External)			
GND PAD	GND	Device Ground			

# **SPECIFICATIONS**

# **MAXIMUM RATINGS**

Parameter	Value	Unit
Storage Temperature Range	−65 to +150	°C
Current per Inductor	15	mA
DC Package Power Rating	500	mW

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

# STANDARD OPERATING CONDITIONS

Parameter	Rating	Unit
Operating Temperature Range	-40 to +85	°C

#### **ELECTRICAL OPERATING CHARACTERISTICS (Note 1)**

Symbol	Parameter	Conditions	Min	Тур	Max	Unit
L <sub>TOT</sub>	Total Channel Inductance			70		nΗ
R <sub>TOT</sub>	Total Channel DC Resistance			45		Ω
Стот_оv	Total Channel Capacitance, 0 V bias	0 V dc; 1 MHz, 30 mV <sub>rms</sub>		17.5	24	pF
<b>C</b> TOT_2.5V	Total Channel Capacitance, 2.5 V bias	2.5 V dc; 1 MHz, 30 mV <sub>rms</sub>		11.5		pF
Vst	Stand-off Voltage	I = 10 μA	5.5			V
ILEAK	Diode Leakage Current	V <sub>IN</sub> = +3.3 V		0.1	0.5	μΑ
VsiG	Signal Clamp Voltage Positive Clamp Negative Clamp	I <sub>LOAD</sub> = 10 mA I <sub>LOAD</sub> = -10 mA	5.6 -1.5	6.8 -0.8	9.0 -0.4	V
Vesd	In-system ESD Withstand Voltage a) Contact discharge per IEC 61000-4-2 standard, Level 4 (External Pins) b) Contact discharge per IEC 61000-4-2 standard, Level 4 (Internal Pins) c) Air Discharge per IEC61000-4-2 standard, Level 4 (External Pins)	Notes 2 and 3	±14 ±2 ±16			kV
V <sub>C</sub>	Clamping Voltage TLP (Note 4) See Figures 4 through 7	Ipp = 8 A Ipp = 16 A Ipp = -8 A Ipp = -16 A		13.7 20 -4.4 -7.6		V
fc	Cut-off frequency Zsource = 50 $\Omega$ , ZLOAD = 50 $\Omega$			345		MHz

- T<sub>A</sub> = 25°C unless otherwise specified.
   ESD applied to input and output pins with respect to GND, one at a time.
- 3. Unused pins are left open.
- 4. ANSI/ESD STM5.5.1 Electrostatic Discharge Sensitivity Testing using Transmission Line Pulse (TLP) Model. TLP conditions:  $Z_0 = 50 \Omega$ ,  $t_p = 100$  ns,  $t_r = 4$  ns, averaging window;  $t_1 = 30$  ns to  $t_2 = 60$  ns.

#### PERFORMANCE INFORMATION

#### **TYPICAL FILTER PERFORMANCE**

 $(T_A = 25^{\circ}C, DC Bias = 0 V, 50 \Omega Environment)$ 

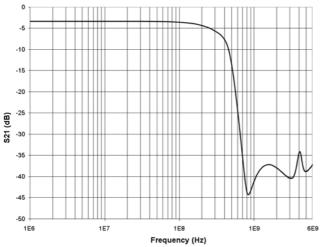


Figure 2. Typical Filter Insertion Loss

# TYPICAL DIODE CAPACITANCE VS. INPUT **VOLTAGE**

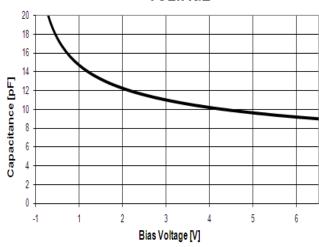
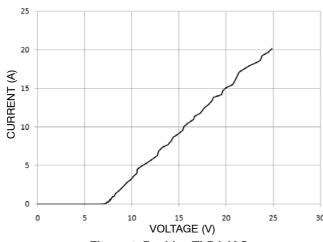


Figure 3. Filter Capacitance vs. Input Voltage (Normalized to Capacitance at 0 VDC and 25°C)

# **ORDERING INFORMATION**

Device	Pins	Marking	Package	Shipping <sup>†</sup>
EMI9408MUTAG	16	LE	UDFN16 (Pb-Free)	3000 / Tape & Reel

<sup>†</sup>For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.



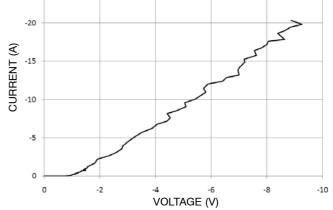


Figure 5. Negative TLP I-V Curve

Figure 4. Positive TLP I-V Curve

# Transmission Line Pulse (TLP) Measurement

Transmission Line Pulse (TLP) provides current versus voltage (I-V) curves in which each data point is obtained from a 100 ns long rectangular pulse from a charged transmission line. A simplified schematic of a typical TLP system is shown in Figure 6. TLP I-V curves of ESD protection devices accurately demonstrate the product's ESD capability because the 10s of amps current levels and under 100 ns time scale match those of an ESD event. This is illustrated in Figure 7 where an 8 kV IEC 61000-4-2 current waveform into a short is compared with TLP current pulses at 8 A and 16 A, also into a short. A TLP I-V curve shows the voltage at which the device turns on, as well as how well the device clamps voltage over a range of current levels. Typical TLP I-V curves for the EMI9404 are shown in Figures 4 and 5 for positive and negative stress respectively. Application note AND9007/D gives more

detail on TLP datasheet parameters, while application note AND9006/D provides a more complete explanation of the use of TLP for understanding protection product characteristics.

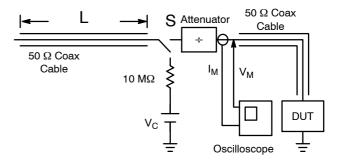


Figure 6. Simplified Schematic of a Typical TLP **System** 

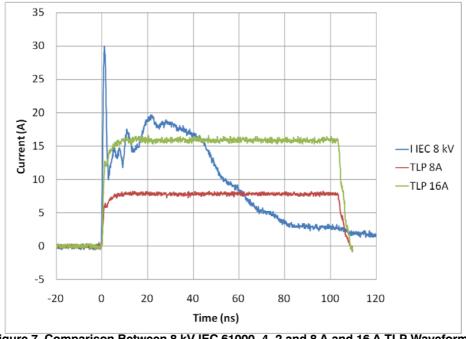


Figure 7. Comparison Between 8 kV IEC 61000-4-2 and 8 A and 16 A TLP Waveforms

//

16X

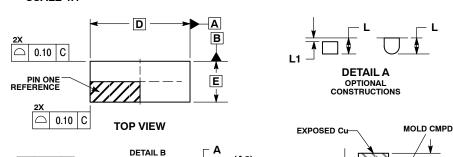
NOTE 4

0.05 C

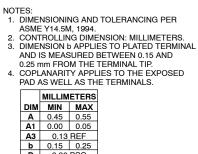
0.05 C

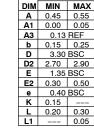


**DATE 18 NOV 2009** 



SEATING PLANE



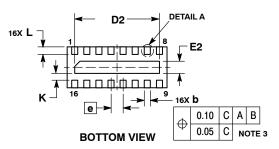


**A3** 

**DETAIL B** 

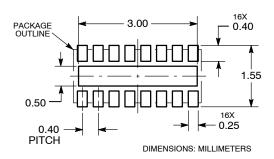
OPTIONAL

CONSTRUCTION



SIDE VIEW

# RECOMMENDED SOLDERING FOOTPRINT\*



<sup>\*</sup>For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

# GENERIC MARKING DIAGRAM\*



XX = Specific Device Code

M = Month Code

= Pb-Free Package

(Note: Microdot may be in either location)

\*This information is generic. Please refer to device data sheet for actual part marking.

Pb-Free indicator, "G" or microdot " ■", may or may not be present.

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